Call for Papers

The SEKM 2019 workshop aims at bringing together experts in software engineering and knowledge management to discuss on relevant results in either software engineering or knowledge management or both. Special emphasis will be put on the transference of methods between both domains.

The topics of interest include (but not limited to):

- Software Engineering Practice
- Web Engineering
- Software Maintenance and Testing
- Formal Methods
- Domain Engineering
- Software Product Line
- Ontology and methodology
- Big Data
- Web-based Education Systems and Learning Applications
- Software Engineering Decision Making
- Search Engines and Information Retrieval
- Requirements engineering
- Cloud Computing
- Knowledge representation and reasoning
- Formal analysis of knowledge and Logics of knowledge
- Knowledge in complex systems and multi-agent systems
- Knowledge extraction and Knowledge integration
- Knowledge-based software engineering
- Knowledge-based and expert system
- Complex system modeling and complexity
- Decision analysis and decision support systems
- Knowledge discovery, data mining, text mining, recommendation system
- Knowledge management strategies and practices
- Web-Based Knowledge Management
Important Dates

- **May 15, 2019** Submission deadline (extended)
- May 25, 2019 Author notification
- June 10, 2019 Camera-ready dues
- July 22-26, 2019 Workshop

Honored General Chairs

- Kokichi Futatsugi, Japan Advanced Institute of Science and Technology, Japan
- Yoshiteru Nakamori, Japan Advanced Institute of Science and Technology, Japan

General Chairs

- Jianwen Xiang, Wuhan University of Technology, China (jwxiang@whut.edu.cn)
- Jing Tian, Wuhan University of Technology, China (jtian@whut.edu.cn)

Program Chairs

- Weiqiang Kong, Dalian University of Technology, China (wqkong@dlut.edu.cn)
- Jiangning Wu, Dalian University of Technology, China (jnwu@dlut.edu.cn)

Program Committee

- Laura Carnevali, University of Florence, Italy
- Jifa Gu, Chinese Academy of Sciences, China
- Shigeru Hosono, NEC Corporation, Japan
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- Roberto Natella, Università degli Studi di Napoli Federico II, Italy
- Wei Sun, Commonwealth Scientific and Industrial Research Organisation, Australia
- Xijing Tang, Chinese Academy of Science, China
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- Jiangning Wu, Dalian University of Technology, China
- Haoxiang Xia, Dalian University of Technology, China
- Xiwei Xu, National Information and Communications Technology, Australia
- Hongbing Yan, East China University of Science and Technology, China
- Chunhui Yang, China Electronic Product Reliability and Environmental Testing Research Institute (CEPREI), China
- Chen Yu, Huazhong University of Science and Technology, China
• Haitao Zhang, Japan Advanced Institute of Science and Technology, Japan
• Min Zhang, East China Normal University, China
• Dongdong Zhao, Wuhan University of Technology, China
• Zheng Zheng, Beihang University, China